COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

the specification of which

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

CHIP ON PHOTOSENSITIVE DEVICE PACKAGE STRUCTURE AND ELECTRICAL **CONNECTION THEREOF**

X is attached hereto.			
was filed on as Application Serial No		and was amended on	
as Application Senain	10	and was amended on	•
specification, including the of acknowledge the duapplication in accordance with the large transfer of the lar	claims, as amended buty to disclose information in Title 37, Code of Figure priority benefits under inventor's certificate at or inventor's certificate.	y any amendment refer ation which is material ederal Regulations, § r Title 35, Untied States listed below and hav	to the patentability of this
, e. e. g. , , , ppeae(e)		plicable	
I hereby appoint the transact all business in the Jiawei Huang Maria Erlinda C. Sarno	Patent and Trademark (Reg. No. 43,330)	- ,, ,	ecute this application and to ewith: (Reg. No. 39,081) (Reg. No. 53,226)
Belinda Lee	(Reg. No. 46,863)		, , ,
SEND CORRESPONDENCE TO:		DIRECT TELEPHONE CALLS TO: (Name and telephone number)	
J.C. Patents, Inc. 4 Venture, Suite 250, Irvine, CA 92618 (949) 660-0761		Jiawei Huang (949) 660-0762	
	-		

COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

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Taiwan R.O.C.

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